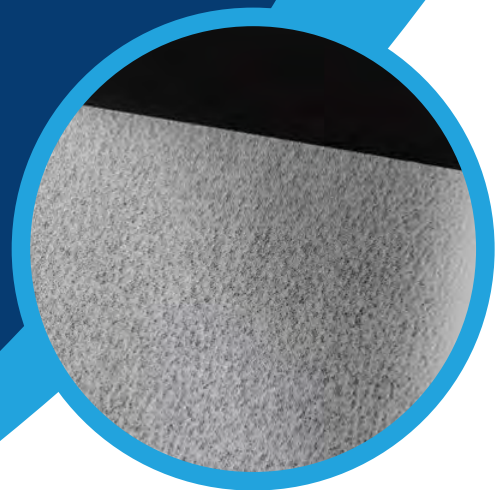










B606L & B606LP

THERMOPLASTIC TPO ADHESIVE FILM

B606 series is a thermoplastic film for perovskite components and thin-film module packaging developed by Betterial. Suitable for perovskite, CIGS, lightweight components.



- 
Non-crosslinked
- 
High Weather Resistance
- 
High Light Transmittance
- 
High Gain
- 
Low Lamination Temperature
- 
Low Water Vapor Transmission Rate
- 
Low Attenuation of Aging Stripping Force
- 
No Release of Small Molecules

Technical Properties

Performance Indicators		Unit	Test Method	B606L	B606LP
Model/Using Instruction		/	/	High Transparency	Deadline
Tensile Strength		MPa	ISO 527-3	≥10	≥10
Adhesion to Glass		N/cm	GB/T 2709	≥80	≥80
Shrinkage Ratio (120°C x 3min)	MD	%	GB/T 29848	≤3.0	≤3.0
	TD	%	GB/T 29848	≤2.0	≤2.0
Light Transmittance	280~380nm	%	ASTM-003	≥75	≤10
	380~1100nm	%	ASTM-003	≥85	≥85
Volume Resistivity		Ω·cm	IEC62788-1-2	≥1*10 ¹⁵	≥1*10 ¹⁵
DC Breakdown Strength		KV/mm	IEC 60243	≥200	≥200
Aging Test DH2000hr	Yellowness Index	ΔYI	GB/T 29848-2018	≤5.0	≤5.0
	Adhesion to Glass	N/cm	GB/T 29848-2018	≥40	≥40
UV Aging Test	120KW·h	ΔYI	GB/T 29848-2018	≤5.0	≤5.0
WVTR	23°Cx85% RH 500um	g/m ² ·day	ISO 15106-3	≤5.0	≤5.0

The technical parameters in Betterial product manual are for reference only. Technical specifications are subject to change without any prior notice.

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